

L Number	Hits	Search Text	DB	Time stamp
166	1240	{flexible near1 (film board substrate carrier tape)) and {flipchip (flip adj chip))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/09/15 15:27
167	291	{{flexible near1 (film board substrate carrier tape)) and {flipchip (flip adj chip))) and {solder adj (resist mask))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/09/15 15:28
168	10525	control\$3 with (flowing flow) with (underfill\$3 resin sealing)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/09/15 15:32
169	0	((flexible near1 (film board substrate carrier tape)) and {flipchip (flip adj chip))) and {solder adj (resist mask))) and {control\$3 with (flowing flow) with (underfill\$3 resin sealing)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/09/15 15:30
170	4	{{flexible near1 (film board substrate carrier tape)) and {flipchip (flip adj chip))) and {control\$3 with (flowing flow) with (underfill\$3 resin sealing)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/09/15 15:30
171	35	{{flexible near1 (film board substrate carrier tape)) and {flipchip (flip adj chip))) and {solder adj (resist mask))) and {(flowing flow) with (underfill\$3 resin sealing)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/09/15 15:32